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(71) Applicant: ENYA MFG. CO., LTD.

8-36, Yoshinodai 2-chome Kawagoe-shi Saitama-ken(JP)

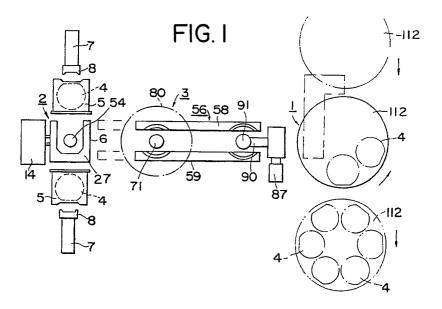
Inventor: Suzuki, Shizuo 20, Nishiwake-cho 1-chome Oume-shi Tokyo(JP)

Representative: Klingseisen, Franz, Dipl.-Ing. et al
Dr. F. Zumstein Dipl.-Ing. F. Klingseisen
Bräuhausstrasse 4
W-8000 München 2(DE)

- (54) Automatic wafer adhering device.
- A wafer adhering device for automatically adhering wafers on a polishing plate for polishing the surface of the wafers.

The wafers are taken out from a wafer cassette one by one, and transferred to an adhesive coating section by a carrying means. The surface of the wafers are coated by the adhesive wax in the coating section. After the adhesive coated wafers are

carried out from the coating section by the carrying means, the wafers are taken out from the carrying means and are reversed the surfaces thereof by a reverse chuck means. The polishing plate is waited on the position where the reversed wafers are arrived, and the wafers are adhered onto the surface of the polishing plate.





EUROPEAN SEARCH REPORT

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DOCUMENTS CONSIDERED TO BE RELEVANT						
ategory		h indication, where appropriate, vant passages		elevant o claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.5)	
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					TECHNICAL FIELDS SEARCHED (int. CI.5) H 01 L B 24 B	
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The Hague 08 May CATEGORY OF CITED DOCUMENTS X: particularly relevant if taken alone Y: particularly relevant if combined with another document of the same catagory A: technological background O: non-written disclosure P: intermediate document T: theory or principle underlying the invention		JMENTS h another	E: earlier patent document, but published on, or after the filing date D: document cited in the application L: document cited for other reasons &: member of the same patent family, corresponding document			